UNIVERSITY OF SOUTHAMPTON

Faculty of Engineering, Science and Mathematics

A group design project report submitted for the award of Master of Engineering

Supervisor: Dr Peter R. Wilson Examiner:

by

Alexander Hornung
Xiaolong Li
Pavlos Progias
Romel Torres
Bo Zhou
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$\underline{\mathbf{ABSTRACT}}$

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List of Symbols

w The weight vector

Acknowledgements

Thanks to no one.

To . . .

Chapter 1

Introduction

1.1 Aim and Background

Nano (get started) mention: D2, Superchip, stuff

1.2 DE2 Board Overview

Nano (get started)

1.3 System Overview

Pavlos (get started) see slides

Chapter 2

Hardware

2.1 Hardware Overview

The hardware part consists of two main blocks: NIOS System on Programmable Controller and the Tester.

The NIOS SoPC coordinates the whole system, writing the data from SD Card into the SRAM for the Tester to read the data from it; retrieving the result that the Tester writes

Dynamically NIOS SoPC Reconfigurable ADC Clock Domain **SRAM** BRIDGE SRAM ARBITER STIM CONTROL FIFOS jţ **FREQUENCY** COUNTER **CHECK** FLASH RE PLL Green boxes are third-party IP cores

Hardware Overview

FIGURE 2.1: Hardware Overview.

back to the SRAM and sending the data to the backend for archiving and reviewing for the users. Its tasks include:

- coordinate the data from multiple sources (SRAM, SD Card, Flash, Serial connection, SPI bus, Ethernet, etc.)
- control the testing process (which is executed by the Tester, frequency counter and ADC)
- send results to the backend
- user interface

The *SRAM arbiter* is the interface between the SoPC, tester and the SRAM by Avalon Memory Mapped Interface (Avalon-MM). It handles the SRAM read and write requests from SoPC and tester.

The Tester contains several HDL blocks which are responsible for the testing process.

- read the command, request and test vector from SRAM
- generate the test input signals for every pin of the DUT
- monitor the output pins of the DUT and write the result into the memory when the it is valid
- offer a dynamically reconfigurable clock for the DUT and its relative interface

The purpose of the *frequency counter* and the *ADC* is that there is a designated pin on the chip which is the output of a ring oscillator. It is preferable that not only the frequency of this clock output is tested, but that the output waveform is also monitored.

2.2 PCB (interface board)

For the chip tester, two PCBs are needed in this project. One which is called B2 has been designed for the virtual designs to be loaded in a slave FPGA. The other is called B1 that is developed as an interface for those real chips are about to be tested. Both PCBs are two layers board and designed by using Allegro 16.3 PCB designer tools. The dimensions of B1 and B2 are 98.93mm*68.5mm and 81.28mm*68.33mm and the minimum wire size is 8mm.

2.2.1 B1 (DUT testing board)

2.2.1.1 DUT

The superchip under test has the following specific features:

- 6 separate design sites
- 24 digital input pins [A0...A23], shared between all design sites;
- 4 digital output pins [Q0...Q23], shared between all design sites;
- 16 separate VDD pins, one dedicated to each design site;
- 1 global GND pin for all design sites and infrastructure circuitry;
- 1 global VDD pin to power the site buffers and I/O pad ring;
- 68-pin JLCC package (with 2 unused pins).

The chip is interfaced with the PCB by a 68WAY PLCC socket. The power is supplied by the 3.3V VDD from the DE2 board. The GND is also connected to the DE2 GND.

The shared I/Os are connected to the powered design site, and disconnected from the other design sites. Hence a controllable power switch is designed with a 4-16 decoder and an integrated power switch array. The Q1 is the output of a ring oscillator. The frequency can be digitally tested by the general I/O. However, to examine the analog properties of this output, an analog part including a buffer, 3^{rd} order Butterworth filter and ADC with their own power supply is also designed.

2.2.1.2 Digital Part

Decoder Although there are 16 design sites to be selected, the data can be shrunk down to 4 bits to save space of the test vector and metadata, since only one site is selected at a time. The decoder we used is 74HC4514, a 4-to-16 line decoder with latch. The input and output are active high.

Switch Array The switch array consists of four TPS2095 quad power-distribution switches. One could simply use a CMOS to realize a switch. However, with thermal sense, current limit and charge pump, the TPS2095 switches are more reliable, stable, smooth (minimum switching current surges) and relatively compact in scale. The operation of a switch is simple: when EN pin is asserted, the OUT pin offers the power with the same voltage in the IN pin. Otherwise the OUT pin is disconnected from the input power. In one TPS2095 chip there are 4 such switches, the EN pins of which are all active high.

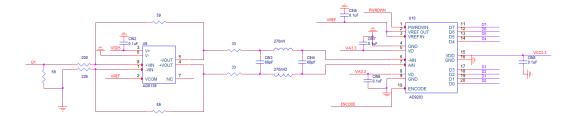


FIGURE 2.2: Analog Part Overview.

2.2.1.3 Analog Part

Buffer An AD8139 differential ADC driver is used as the front buffer of the ADC. It is an ultralow noise, high performance differential amplifier with rail to rail output from Analog Devices. The designed gain of the buffer is 0.295, and the differential gain is approximately 0.14.

ADC The 8-bit, 100MSPS ADC is used to convert the analog signal. The encode clock is the clock from the DE2 board (100MHz by default). A power-down function select is also connected to the FPGA for shutting down the ADC when its not in use. The ADC signal wires should be placed far away from the other wires for minimum interference; and they should also be placed parallel to each other to have similar length for better signal integrity. However, since the pin density is too high of the HSMC connector we used, it is inevitable that the ADC wires are closed to the other wires. The ADC is placed on the other side of the PCB board for a better result.

Butterworth Filter To minimize the high frequency noise, a third-order low pass Butterworth filter is designed. With three poles, the attenuation is $-60^{dB}/decade$ on signals higher than the cut-off frequency. The filter topology used here is balanced ladder topology. Automatic design tool Elsie is used for designing the parameters of the RCI circuit. The cut-off frequency is 40MHz.

Separate Power Supplies The buffer and ADC are separately powered from the other parts of the board. The AD8139s power ranges from 5V to 12V, and the ADC ranges from 2.7V to 3.6V. Two low dropout regulators (LDP), ADP3335 and ADP3333 are used to offer 5V and 3.3V voltages respectively. The supply voltage of these two LDP ranges from 2.6V to 12V. Their load currents are up to 500mA and 300mA respectively.

2.2.2 B2 (Virtual design board)

2.2.2.1 Slave FPGA

Slave FPGA is the core chip of the virtual design board. It can be used for programing designs when they are going to be tested. An Altera Cyclone III FPGA will be implemented as the slave FPGA.

Cyclone III (EP3C25E144) belongs to Cyclone III device family. With densities ranging from about 5,000 to 200,000 logic elements (LEs) and 0.5Mb to 8Mb of memory for less than $^{1}/_{4}V$ of static power consumption, Cyclone III devices makes it easier to meet the power budget (Altera Corporation, 2011).

The reason for choosing Cyclone III is their lowest power, high functionality with the lowest cost. 144 pins are enough for this design. I/O pins on the Cyclone III are grouped together into I/O banks, and each bank has a separate power bus. There are eight I/O banks, as shown in Figure 1 (Altera Corporation, 2011). All single-ended I/O standards are supported in all banks except HSTL-12 Class II which is only supported in column banks. The same case can be found in all differential I/O standards.

Each I/O banks of Cyclone III has a VREF bus to accommodate voltage-referenced I/O standards. Connect the VREF pin of each group to the appropriate voltage. In this design three voltage levels, which VCCIO = 3.3V, VCCINT = 1.2V and VCCA = 2.5V, are necessary. Proper bypassing and decoupling technique for the power pins is very important for reliable design operation. In this case, additional decoupling capacitance is needed. The VCCINT, VCCIO and ground pins should add as many as $0.2\mu F$ power-supply decoupling capacitors as possible. So $0.01\mu F$ capacitor for VCCIO and $0.1\mu F$ for VCCINT seems to be appropriate. Note that all the capacitors should be place close enough to the power pins.

In regard of the Cyclone III configuration, the Cyclone II device uses SRAM cells to store configuration data. EP3C25E144 can only be configured in Fast Active serial (AS) mode.

Configuration data is loaded into Cyclone III at each DCLK cycle. As soon as the device receives all data, the device releases the open-drain CONF_DONE pin, which is pulled high by an external 10- pull-up resistor. The CONF_DONE pin transits low-to-high to indicate that configuration is complete and initialization of the device can begin. The CONF_DONE pin must have a 10- pull-up resistor for initialization.

Pulling the nCONFIG pin low can begin reconfiguration and this pin must be low for at least 500ns. The Cyclone III device is reset when nCONFIG is pulled low. Meanwhile, the device will pulls nSTATUS and CONF_DONE low and I/O pins are tri-stated. When nCONFIG returns to high and nSTATUS is released, reconfiguration begins.

The clock source for initialization is either a 10MHz (typical) internal oscillator or an optional CLK pin. In this situation, an external oscillator (A TXC-50MHz oscillator is going to be introduced later) will be implemented as the clock source. The required clock for initialization in Cyclone III is 3, 185 and the maximum CLK frequency is 133MHz.

The configuration mode is selected by driving the MSEL pins either low or high. The MSEL pins can be powered by VCCIO and GND. For AS mode, MSEL [1] should be pulled up by connecting to VCCIO. MSEL [0] and MSEL [2] are pulled down by connecting to GND. The MSEL pins have 9 internal pull-down resistors that are always active.

The maximum active master frequency for Cyclone III is 30MHz typically and device only work with serial configuration devices that support up to 40MHz.

In AS mode, Cyclone III reads the configuration data providing by serial configuration (A Spansion SPI Flash is going to be introduced later) via a serial interface. The serial configuration device controls the configuration interface.

There are four pins on the serial configuration devices:

- Serial clock input (DCLK)
- serial data output (DATA)
- As data output (ASDI)
- Active-low chip select (nCS)

Connect these four pins to Cyclone III device pins, as shown in Figure 2.

A 25Ω series resistor must connect a between serial configuration device and the Cyclone III device at the near end of the serial configuration device for DATA [0] when configure the Cyclone III device in the AS mode. The 25Ω resistor works to minimize the driver impedance mismatch with the board trace and reduce the overshoot seen at the Cyclone III device input pin DATA [0].

The maximum trace length between Cyclone III device and the serial configuration device, in another words, the CLK, DATA [0], NCSO and ADSO pins, must less than 10in. In the B1 PCB designing, only 8mm is used.

Cyclone III device uses a 40MHz internal oscillator to generate DCLK to controls the entire configuration cycle and provide timing for the serial interface.

By driving the nCSO output pin low, which connect to nCS pin of the configuration device, the Cyclone III device enables the configuration device. DCLK and DATA [1] pins are used to send operation commands and read address signals to the serial configuration device. The configuration device sends data on DATA pin which connects to

the DATA [0] pin of the Cyclone III device. After all the configuration bits are received, cyclone III releases the open-drain CONF_DONE pin with a 10Ω pull-up resistor. The CONF_DONE pin must have an external 10Ω resistor for the device to initialize.

2.2.2. Serial Configuration Device

Cyclone III FPGAs are programmable logic devices used for basic logic functions, chip-to-chip connectivity, signal processing, and embedded processing. They can be programmed and configured by a microprocessor, JTAG port, or directly bay a serial PROM or flash. Spansion SPI (Serial Peripheral Interface) flash S25FL064K can configure the FPGA easily at power-up (Spansion, 2011).

The three stages of the configuration cycle are power-on reset, configuration, and initialization. When the FPGA enters power-on rest (POR), it drives the nSTATUS signal low to indicate it is busy, drives the CONF_DONE signal low to indicate the configuration has not been completed, and tri-states all I/O pins. All pins will be released after POR.

The DCLK generated by the FPGA device control the configuration data transferring. The CONF_DONE pin will be released with pulling high by an external pull-up resistor after all configuration data is transferred to the FPGA. The FPGA enters user mode after internal initialization.

The SPI is a simple four-pin synchronous interface protocol which enables a master device and one or more slave devices to intercommunicate. Four signal wires are:

- Master Out Slave In (MOSI) signal generated by the master (data to slave)
- Master In Slave Out (MISO) signal generated by the slave (data to master)
- Serial Clock (SCK) signal generated by the master to synchronize data transfers
- Slave Select (SS) signal generated by master to select individual slave devices (also known as Chip Select (CS) or Chip Enable (CE))

Figure 3 displays a simple block diagram of the connection between FPGA and SPI flash, as well as the HSMC header and JTAG programming the SPI flash from a host PC.

Figure 4 displays the details of the connection between SPI flash and FPGA. According to the introduction of Cyclone III, we can acquire the whole routing of FPGA, SPI flash and the HSMC header (A Samtec ASP header will be introduced later).

The TMS, TDI, TDO and TCK pins of Cyclone III device are used to operating in the IEEE Std. 1149.1 BST. The TDO pin is powered by VCCIO (3.3V). TDI and TMS are powered by VCCA (2.5V).

The header for JTAG and the header for SPI Flash In-system is use the same HSMC header with 172 pins which is quite enough for these two headers.

2.2.2.3 External Oscillator

As mentioned in the Cyclone III part, an external oscillator is needed as the clock source to provide certain frequency for the FPGA. A 50MHz oscillator of TXC will be implemented. The typical clock frequency for Cyclone III device is 30HMz and the maximum is 40MHz. The TXC DEL04 oscillator is a sealed clock crystal oscillator unit with high precision characteristic covering up to wide frequency range (1MHz) to 170MHz, which is appropriate for the FPGA. The supply voltage range is $1.8V \sim 5V$ (TXC).

2.2.2.4 Voltage Regulator

The B2 board needs at least three different voltage levels, as mentioned before, VCCIO = 3.3V, VCCINT = 1.2V and VCCA = 2.5V. The external power source is provided by the main FPGA DE2-115 board at 3.3V. Hence two voltage regulators are used to transfer 3.3V into 1.2V and 2.5V.

1.2V Voltage Regulator LD1117 The LD111712 is a low drop voltage regulator able to provide up to 800mA of output current, available in adjustable version (). The device is supplied in DPAK surface mount package optimize the thermal characteristics even offering a relevant space saving effect. A very common 10 minimum capacitor is needed for stability (ST Microelectronics, 2012).

Figure 5 is the application circuit for 1.2V output.

2.5V Voltage Regulator TPS78225 The TPS78228 is a low dropout linear voltage regulator designed by TI. The enable pin (EN) is compatible with standard CMOS logic while the low drop output is stable with any capacitor greater than 1. The device requires minimal board space for miniaturized packaging and potentially small output capacitor (Texas Instruments, 2008).

The enable pin is active high and is compatible with standard and low-voltage CMOS levels. Therefore if the shutdown capacitor is not necessary, enable pin can connect to the IN pin as shown on Figure 6.

2.2.2.5 HSMC Header

The Altera High Speed Mezzanine Card (HSMC) specification defines the electrical and mechanical properties of the HSMC adapter inter face for FPGA-based motherboards. The HSMC connector is based on the Samtec 0.5mm pitch, surface-mount QTH/QSH family of connectors (Altera Corporation, 2009). Two versions can are used in FPGA board. ASP-122953-01 Socket for the host boards and ASP-122952-01 Header for Mezzanine Cards (slave boards).

Figure 7 is the diagram for HSMC header. The clock-data-recovery differential signals in Bank 1 are the highest frequency signals. Signals between the HSMC connector and the host board FPGA device are intended to be D/C coupled. The JTAG, a system management bus (SMBus), and clock signals are also dedicated in Bank 1. In banks 2 and Bank 3, there are main CMOS/LVDS interface signals, including LVDS/COMS clocks, as well as both 12V and 3.3V power pins.

The host board is any board with an FPGA connected to one or more HSMC interface. In this project it is DE2-115 developed board. The interconnect I/O pins available on the HSMC connector can have all possible I/O standard and logic features that can be supported by the host FPGA since FPGAs are configurable devices. However basically they are limited by the wire types on the board.

The HSMC connectors provided the interface between host and slave boards. The "header" part (ASP-122952-01) on slave board plugs into the "socket" part on the host board. The host board provides +12V DC and +3.3V DC power to the slave board via the HSMC connector. In addition to power and clock signals, the host board provides access to JTAG, high speed serial I/O, and single-ended or differential I/O via the HSMC connector.

The HSMC connector has a total of 172 pins, including 121 signal pins (120 signal pins + 1 PSNTn pin), 39 power pins, and 12 ground pins. The ground pins are much larger than the power pins and are located between the two rows of signal and power pins. Figure 7 is the modules for HSMC connectors.

The ASP - 122952 - 01 header provides 160 total pins and 12 ground plane connection pins down the center. Bank 1 has 40 pins with every third pin removed. Bank 2 and 3 have 60 pins each as no pins are removed. Host boards provide transceivers to Bank 1 which is not used in this project. Single-ended signals are provided to Bank 2 and 3. Typically, the single-ended signals are capable of differential signalling such as LVDS.

The JTAG signals are intended to connect to dedicated JTAG pins on the host FPGA and be part of the JTAG chain. The JTAG signals TCK, TMS and TDI are intended to be output from host board while JTAG TDO should be the input to host board as Figure 4 before.

Tables A.1 and A.2 in the appendix show the pin-outs for the HSMC header on B1 and B2 boards, respectively.

2.3 Chip Tester (Verilog Module)

Joey (and a bit Alex)

mention: reconfigurable clock domain, synchronizing DC FIFOs

- test controller
- $\operatorname{mem_if}$
- stim
- check
- dut_if (and its pipeline)
- reconfigurable PLL

2.4 SRAM Arbiter (sram_arb_sync.v)

Pavlos

Chapter 3

SoPC

3.1 Overview

Alex

- Altera-provided Peripherals
- Nios II core
- Avalon-MM bus (at least the signals we use)

3.2 SRAM_bridge

Alex

3.3 test_runner

Alex

3.4 Frequency Counter

3.4.1 Overview and Specification

The frequency counter module of the Superchip tester is connected to the oscillator found in the superchip designs, to measure its output frequency.

Chapter 3 SoPC

According to specification for the academic year 2011 - 12, the ring oscillators found in the teams' superchip designs have a basic frequency of 1MHz and an offset frequency of the teams' ID number multiplied by 250kHz (The University of Southampton, 2011). For 16 teams, the frequency range would be 1250kHz - 5000kHz.

3.4.2 Functionality

Since the clock of the FPGA is significantly faster than the oscillator frequency, the frequency counter designed for this project counts the number of the oscillator signal edges over a given number of FPGA clock cycles. The frequency counter consists of three modules, a 24-to-1 multiplexer, the measurement module and a control module. When the frequency counter is enabled, the processor provides it with the required number of clock cycles. The counter starts counting the rising edges of the input signal and after it stops counting, once the specified number of clock cycles has been reached, it raises an interrupt signal for the data to be read from the processor. While the active-low nReset signal is enabled, the counter ceases all function and all registers and outputs are nulled.

Multiplexer The purpose of the multiplexer is to connect the measurement module to the correct pin of the chip under test, to achieve better reconfigurability. In order to provide compatibility of the design with chips whose oscillator output can be different, the multiplexer is connected to all design outputs and only connects the one specified by the processor to the measurement module.

Measurement Module The measurement module of the frequency counter provides the main functionality of the design, measuring the number of input signal periods over a specified time. This module is provided with the target number of clock cycles and the input signal (to be measured). In order to maintain signal integrity, since the input signal is effectively crossing a clock domain, the design contains a synchroniser stage, to synchronise the input signal with the FPGA clock. When the module is enabled, the edge counter increments its value on every rising edge of the input signal. Once the module has gone through the required clock cycles, it stops counting input signal periods and an *count_over flow* flag is raised.

Control Module The frequency counter control module handles the communication and the input setup data from the processor, as well as the the output data from the measurement module. It provides an Avalon Memory Mapped slave interface for communication with the NIOS II processor as well as an Avalon Interrupt signal interface (IRQ) and a busy signal.

Chapter 3 SoPC 15

Before starting the frequency measurement procedure the NIOS core writes data to the frequency counter, to specify parameters such as the duration of the measurement. When the *write* signal in the Avalon interface is active, the register specified on the address bus is written with the data on the data bus.

The internal *enable* signal to start the process is activated by the controller when a dedicated register is written with a unity value and kept high for a single clock cycle. As long as the frequency counter is enabled and counts periods of the input wave, the controller keeps the *busy* signal high to inform the NIOS II core that it is processing.

The data stored on the registers of the controller are kept steady and provided to the other modules of the frequency counter. Once the measurement module is done and the done flag is enabled, the controller stores the count value to the relevant register and raises the *irq* signal to the processor.

Following an interrupt request, the processor starts reading values from the registers of the frequency counter module. When the *read* signal in the Avalon interface is active, the module outputs the data on the register specified on the address bus to the processor. Meanwhile, when data is read from the registers, the *readdatavalid* signal is high as well. When the data contained in the registers is read after a calculation procedure and an interrupt request to the processor, the *irq* signal is cleared.

$3.5 \quad ADC$

Pavlos

Chapter 4

Embedded Software

4.1 Bootloader and Operating System

Alex

- u-boot
- uClinux (w Linux 3.3)

4.2 Drivers

Alex

- $\hbox{- fcounter} \\$
- test_runner (and arbiter)
- $\operatorname{-}\operatorname{adc}$
- Character LCD driver
- sram_access (not really driver, simply memory mapped)

4.3 confrd

Alex

- parser, lcd, api access, hardware access, ...

4.4 SPI Flash Configuration

Romel

4.5 Configuration File Format

Alex (get started)

Chapter 5

Backend Software

5.1 Overview

In order to store and show the results sent from the **FPGA** in a database a web server was developed; this server provides the user an interface where they can see and manage the results, upload designs and configuration files to the **chip tester** and administrate the database where the results have been stored. Basically the web server "serves" the content to the user through the Internet to a web page, where the users (administrators or students) can check the results of their designs or manage the results stored in the database. The users load their designs into the web server and then whenever the FPGA sends a "download configuration files request" to the server, it will send the files to the FPGA (if available).

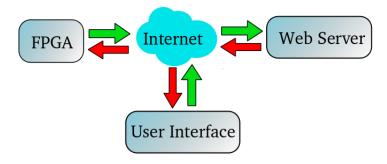


Figure 5.1: Interaction between elements in the system

Nowadays almost every programming language provides libraries to develop web servers; for this application we required a robust, easy to use, programming language. Java, Python, PhP, Ruby, Perl are the most common languages used to develop servers. We

decided to use Ruby with itsweb framework Sinatra. Ruby is a general-purpose objectoriented programming language easy to learn and powerful, Sinatra is a Domain Specific Language (DSL) for quickly creating web applications in ruby.

UNICORN INSTEAD OF WEBBRICK, WHY?

5.2 API

The way the FPGA communicates to the server is through the Hypertext Transfer Protocol (HTTP). In the client-server model HTTP works as a request-response protocol. The FPGA and the user web browser act as clients, while the application running on the computer hosting the web site is the server. The FPGA and web browser submit HTTP request messages to the server. The server stores content, provides resources such as configuration files, sends emails, manages the database on behalf of the clients. HTTP defines 9 methods indicating the action to be performed on a resource: HEAD, GET, POST, PUT, DELETE, TRACE, OPTION, CONNECT and PATCH. To develop this application we have used only three of this methods GET which retrieves information from the server, POST which sends data to the server as part of the request and DELETE which deletes resources. The figure 5.2 shows an example of the get method, both in the server and in the browser.

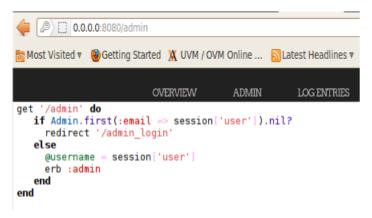


FIGURE 5.2: Example of the HTTP method GET in the browser and in the server

In order to communicate from the FPGA to the server a data exchange language is needed; the most popular data exchange language is "XML", nevertheless, adding the xml parsing libraries in the μ Clinux would slow down the parsing data process due to the complexity of the xml libraries. JSON, is a lightweight data exchange library supported in C (for the FPGA) and ruby (for the Server) therefore it was perfect for our application. The figure 5.3 shows an example of a message in the JSON format that would be sent from the FPGA to the server.

The table 5.1 shows the "URL" the FPGA uses to connect to the server, and a brief description of what each command does in the server.

FIGURE 5.3: Example of a JSON message

Type	Link	Command
post	/api/result	Stores the results sent from
		the fpga in the table Results
		in the database
post	/api/result/:result_id/design	Stores in the table De-
		sign_Results associated to
		the result (in the table Re-
		sults) identified with the id:
		result_id (results summarized)
post	/api/result/:result_id/design/:design_id	Stores in the table Frequen-
	/measurement/frequency	cyMeasurement associated to
		the design_result identified
		with the id design_id (infor-
		mation related to the fre-
		quency of the oscillator in the
		design)
post	/api/result/:result_id/design/:design_id	Stores in the table AdcMea-
	/measurement/adc	surement associated to the de-
		sign_result identified with the
		id design_id (information re-
		lated to the sampled oscillator
		in the design)
post	/api/result/:result_id/design/:design_id	Stores in the table Test_vector
	/vector	associated to the design_result
		identified with the id de-
		sign_id (more information
		about the results of the test)
get	/api/vdesign	Download a configuration file
		into the fpga

Table 5.1: API for the communication between the fpga and the server

5.3 "Server" (Sinatra stuff, database, etc)

Inside the folder called **server** are all the files regarding to our back-end application. In the folder **public** are the stylesheets for the web page styling, and the images displayed in the page, in **uploads** are all the files uploaded in the server by the users, in **utils** are

```
+server
   +public
      +css
      +ima
   +uploads
   +utils
   +views
 config.ru
-config.yml
-database.rb
-email.rb
-Gemfile
-init.rb
-Rakefile
-s.css
-server.rb
-s.scss
-unicorn.conf.rb
```

FIGURE 5.4: Folder structure of the server

Email	Permission	Password_hash
String	Integer	BCryptHash

Table 5.2: Admin table in the database

some utility scripts written in ruby such as secure password generation, **views** contains all the views in the page that the different users can have access to.

5.3.1 Database

Datamapper is an ORM (Object-Relational Mapping) that maps objects written in ruby to any supported database, thus giving freedom to the administrators of the system to use any database system (such as MySQL, SQLite, Postgres,...) to choose the database the administrator simply has to change the configuration parameters in the file **config.yml** (found in the server folder) as shown in the figure 5.5 where the administrator has set up the database system with MySql.

```
database:
    type: mysql
    user: root
    password: chip1234
    database_name: ChipTester
    address: localhost
```

FIGURE 5.5: Database system selection using the config.yml file

In the table Admin 5.2 is stored the administrators of the database. The email field is the email used t log in, the Permission field is the level of authority that each administrator has. It can be either 0 or 1 (where 0 means that it can add more administrators to the system) and the password_hash field is a hash related to the user password (more in the server security section)

The initial administrator is configured in the archive config.yml as shown in the figure 5.6. For security reasons the password of the initial administrator must be encrypted

Id	Email	Team	$File_name$	Is_valid	$Created_at$	$Updated_at$
Serial	String	Integer	String	Boolean	Date	Date

TABLE 5.3: File Upload table in the database

Id	Type	Message	File	Line	$Created_at$	$Updated_at$
Serial	Integer	String	String	Integer	Date	Date

TABLE 5.4: Log Entry table in the database

Id	Team	Academic Year	$Created_at$	$Updated_at$	Virtual
Serial	Integer	String	Date	Date	Boolean

Table 5.5: Result table in the database

Id	Created_at	$Updated_at$	Triggers	$File_name$	Clock_Frequency	Design_name
Id	Date	Date	String	String	String	String

Table 5.6: Design Result table in the database

Trigger_timeout	Has_run	Fail	$Created_at$	$Updated_at$
Boolean	Boolean	Boolean	Date	Date

Table 5.7: Test Vector Result table in the database

using the script **pass.rb** located in server/utils. Whenever the server is run by the first time, or the database has been created again this user will be mapped into the database, granting always access to the administrator.

```
#Master email address and password
admin:
    username: prw@soton.ac.uk
    password: $2a$10$KVIbrolv6wwL0CoHYt.L2.EQab4kGVTWdmRgz2YRV4SEe56PQErNG
    permission: 0
#Maximum permission in the databse
```

FIGURE 5.6: Initial Master Admin selection using the config.yml file

The File Upload table 5.3 in the database stores the configuration files that has been uploaded to the server by the students.

The Log entry table stores all the logs sent from the FPGA to the server, this table is displayed to the user in the web page.

The result table has

Id	Type	$Input_vector$	$Expected_result$	Actual_result	Cycle_count
Serial	Integer	String	String	String	Integer

5.3.2 Security

BCRYPT

Id	Frequency	$Created_at$	$Updated_at$
Serial	Float	Date	Date

Table 5.8: Frequency Measurement table in the database

5.3.3 Views

5.4 E-Mails

Romel

5.5 Remote Reconfiguration

Romel

5.6 User Interface

In order to provide an interface between the Superchip Tester, the database and the user, a webpage has been set up to provide the required functionality. The website provides access to the results database, but also allows the user to upload configuration files for the device.

The design of the webpage is based on a website template found on CSS Templates, altered to provide a look and functionality suitable for interface to the chip tester.

The webpage is laid out in a user-friendly and simple manner, with a navigation bar at the top of the page through which the user can browse the pages of the chip tester interface. The four entries in the navigation bar are *Overview*, *Admin*, *Log Entries* and *Upload Files*. In the main part of the screen, the content of the current view is displayed.

In figure 5.7, a screenshot of the website showing the first navigation option, *Overview*. This view takes the user to an overview of the database where the superchip test results are stored. The table contains seven columns, displaying the number of the team, the date when the test was run and the relevant academic year, the result of the test, the date and time when the entry was updated and whether the design was virtual or actual.

Clicking on the result of an entry takes the user to a more detailed view of that specific run. In this view the user can also see the measured frequency of the oscillator of the design and the name of the design. If the design has failed the test, clicking on the failed result of the test takes the user to another view, where they can monitor the failed test in more detail. This page provides information on the failed test, to help identify

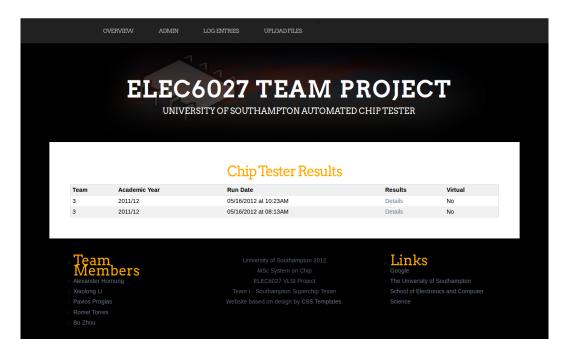


FIGURE 5.7: The ChipTester webpage showing an overview of the database.

the reason of the failure. In specific, the user can see information about the test run, including the input vector to the design and a comparison between the expected and the actual result.

The second option of the navigation bar, *Admin* prompts the user to enter their administrator credentials and takes them to the administrator view page. From this page, an administrator can reset the database, e-mail the results to a specified e-mail address, go to a detailed view of the database or add a new administrator to the system.

more stuff about manage database

Choosing the third option on the navigation bar, *Log Entries*, take the user to yet another webpage that I can't explain what it does.

The last option of the navigation bar, *Upload Files* allows the user to upload a configuration file to the server. The user is asked to enter their e-mail and their team number and a file to upload.

Chapter 6

Some other yet-unnamed section

6.1 Detailed resource usage on FPGA

stuff.

6.2 Rough bill of materials (or more like, cost of each board)

more stuff.

Appendix A

Pinout Tables

Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name
39	ENCODE	48	A0	50	A1
54	A2	56	A3	60	A4
62	A5	66	A6	68	A7
72	A8	74	A9	78	A10
80	A11	96	A12	98	A13
102	A14	104	A15	108	A16
110	A17	114	A18	116	A19
120	A20	122	A21	126	A22
128	A23	132	Q0	134	Q1
138	Q2	140	Q3	144	Q4
146	Q5	150	Q6	152	Q7
156	Q8	158	Q9	157	Q10
155	Q11	151	D0	149	D1
145	D2	143	D3	139	D4
137	D5	133	D6	131	D7
127	Q12	125	Q13	121	Q14
119	Q15	115	Q16	113	Q17
109	Q18	107	Q19	103	Q20
101	Q21	97	Q22	95	Q23
91	SEL1	89	SEL2	85	SEL3
83	SEL4	79	PWRDWN	45	VCCIO
51	VCCIO	57	VCCIO	63	VCCIO
69	VCCIO	75	VCCIO	81	VCCIO
87	VCCIO	93	VCCIO	99	VCCIO
105	VCCIO	111	VCCIO	117	VCCIO
123	VCCIO	129	VCCIO	135	VCCIO
141	VCCIO	147	VCCIO	153	VCCIO
159	VCCIO	161	GND	162	GND
163	GND	164	GND	165	GND
166	GND	167	GND	168	GND
169	GND	170	GND	171	GND
		172	GND		

Table A.1: Pin-outs for the HSMC header on B1 board.

Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name
35	TCK	36	TMS	37	TDO
38	TDI	39	Ded_Clock	41	CONF_DONE
42	nSTATUS	43	nCONFIG	44	nCE
48	IO1	50	IO2	54	IO3
56	IO4	60	IO5	62	IO6
66	IO7	68	IO8	72	IO9
74	IO10	78	IO11	80	IO12
84	MOSI	86	MISO	90	nCS
92	SCK	96	IO13	98	IO14
102	IO15	104	IO16	108	IO17
110	IO18	114	IO19	116	IO20
120	IO21	122	IO22	126	IO23
128	IO24	132	IO25	134	IO26
138	IO27	140	IO28	144	IO29
146	IO30	150	IO31	152	IO32
156	IO33	158	IO34	157	IO35
155	IO36	151	IO37	149	IO38
145	IO39	143	IO40	139	IO41
137	IO42	133	IO43	131	IO44
127	IO45	125	IO46	121	IO47
119	IO48	115	IO49	113	IO50
109	IO51	107	IO52	103	IO53
101	IO54	97	IO55	95	IO56
91	IO57	89	IO58	85	IO59
83	IO60	79	IO61	77	IO62
73	IO63	45	VCCIO	51	VCCIO
57	VCCIO	63	VCCIO	69	VCCIO
75	VCCIO	81	VCCIO	87	VCCIO
93	VCCIO	99	VCCIO	105	VCCIO
111	VCCIO	117	VCCIO	123	VCCIO
129	VCCIO	135	VCCIO	141	VCCIO
147	VCCIO	153	VCCIO	159	VCCIO
161	GND	162	GND	163	GND
164	GND	165	GND	166	GND
167	GND	168	GND	169	GND
170	GND	171	GND	172	GND

Table A.2: Pin-outs for the HSMC header on B2 board.

Bibliography

Altera Corporation. High Speed Mezzanine Card specification, June 2009. Revision 17.

Altera Corporation. Cyclone III Device Handbook, volume 1. December 2011.

Spansion. Connecting Spansion SPI Serial Flash to Configure Altera FPGAs, 16 November 2011. Revision 4.

ST Microelectronics. LD1117xx datasheet, Adjustable and fixed low drop positive voltage regulator, 13 February 2012. Datasheet.

Texas Instruments. TPS782 150mA, Ultra-low Quiescent Current, Low-Dropout Linear Regulator Datasheet, September 2008.

The University of Southampton. D2 Specification 2011-12, 2011.

TXC. Oscillators 7X5mm SMD CMOS CXO 7W Series Datasheet.